

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company



N-Channel Silicon MOSFET General-Purpose Switching Device Applications

Features

- Ultrahigh speed switching
- 4V drive

Specifications

Absolute Maximum Ratings at Ta=25°C

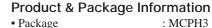
Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		30	V
Gate-to-Source Voltage	VGSS		±20	V
Drain Current (DC)	ID		1.8	А
Drain Current (Pulse)	IDP	PW≤10µs, duty cycle≤1%	7.2	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm ² ×0.8mm)	0.8	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

This product is designed to "ESD immunity $< 200V^*$ ", so please take care when handling.

* Machine Model

Package Dimensions

unit : mm (typ) 7019A-003

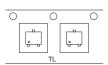


: MCPH3

JEITA, JEDEC : SC-70, SOT-323
Minimum Packing Quantity : 3,000 pcs./reel

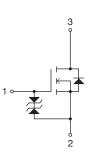
Packing Type : TL

Marking

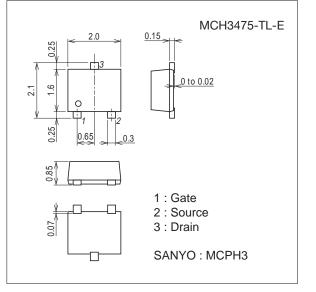


FG

Electrical Connection



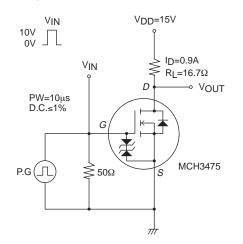
SANYO Semiconductor Co., Ltd. http://semicon.sanyo.com/en/network



Electrical Characteristics at Ta=25°C

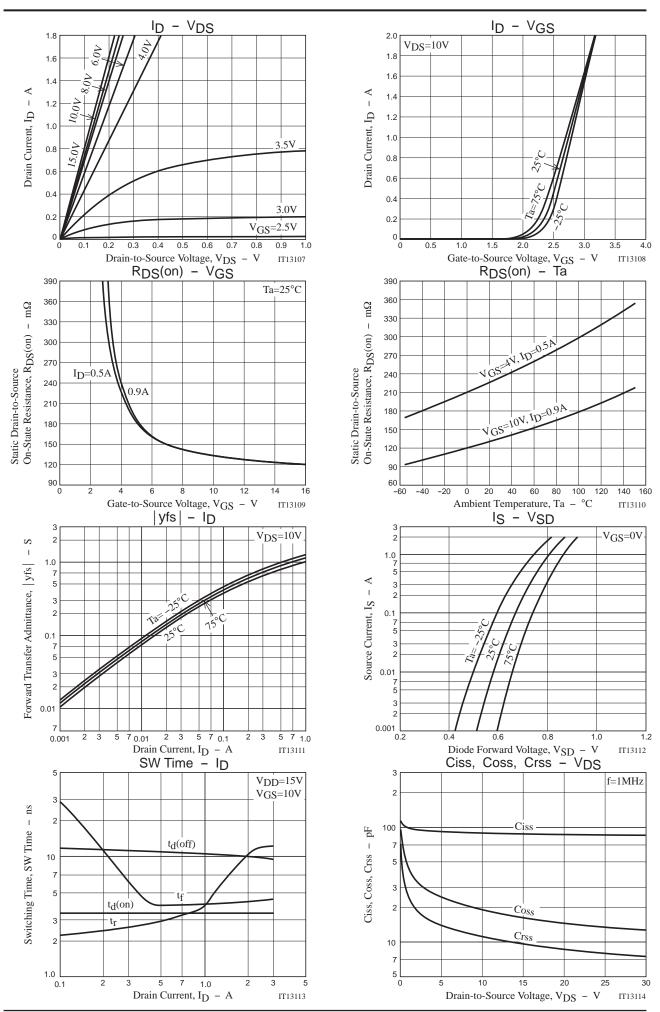
Parameter	Ourseland	0	Ratings				
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	30			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±16V, V _{DS} =0V			±10	μΑ	
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	1.2		2.6	V	
Forward Transfer Admittance	yfs	V _{DS} =10V, I _D =0.9A	0.66	1.1		S	
Otatia Ducia ta Ocuma Ora Otata Daciatana a	R _{DS} (on)1	I _D =0.9A, V _{GS} =10V		135	180	mΩ	
Static Drain-to-Source On-State Resistance RDS(on)		ID=0.5A, VGS=4V		230	330	mΩ	
Input Capacitance	Ciss			88		pF	
Output Capacitance	Coss	VDS=10V, f=1MHz		19		pF	
Reverse Transfer Capacitance	Crss]		11		pF	
Turn-ON Delay Time	t _d (on)			3.4		ns	
Rise Time	t _r			3.6		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit.		10.5		ns	
Fall Time	tf	1		4.0		ns	
Total Gate Charge	Qg			2.0		nC	
Gate-to-Source Charge	Qgs	V _{DS} =10V, V _{GS} =10V, I _D =1.8A		0.33		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		0.29		nC	
Diode Forward Voltage	VSD	IS=1.8A, VGS=0V		0.86	1.2	V	

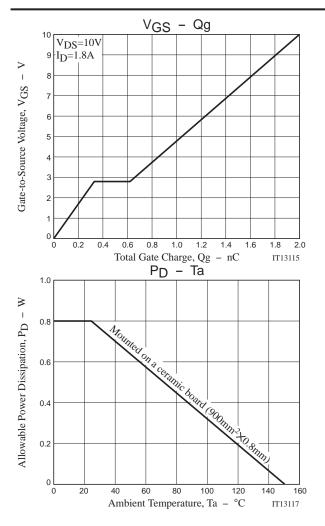
Switching Time Test Circuit

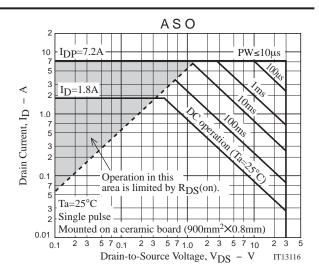


Ordering Information

0				
Device	Package	Shipping	memo	
MCH3475-TL-E	MCPH3	3,000pcs./reel	Pb Free	







Taping Specification MCH3475-TL-E

1. Packing Format

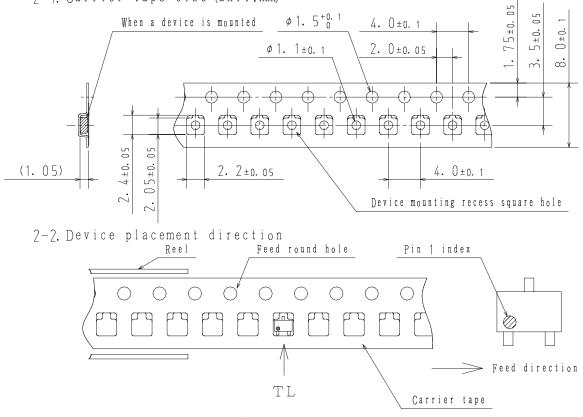
Packing method (unified filling) The form of a label may change in physical distribution process. Image: Structure filling fill	Package Name	Carrier Tape	Maximun Number of devices contained (pcs)			Packing format		
Michael Michael Dimensions:mm (external) Dimensions:mm (external) Packing method Reel label, Inner box label Quart is mm) Quart is mm) Image: Comparison of the compa		Туре	Reel	Inner box	Outer box	Inner BOX (C-1) Outer BOX (A-7)		
Packing method Dimensions:mm (external) Dimensions:mm (external) Packing method Reel label, Inner box label Quart itym Image: Construction of the terminal is lead free. Image: Construction of the terminal is lead free.	МСРН 3	MCPH3	3,000	15,000	90,000	5 reels contained 6 inner boxes contained		
Packing method Reel label, Inner box label (unit:mm) Outer box label It is a label at the time of factory shipments. The form of a label may change in physical distribution process.						Dimensions:mm (external) Dimensions:mm (external)		
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Type No. Image: Constraint of the surface treatment of the terminal is lead free.	0	<		<	6	<u>59</u>		
Label JEITA Phase		No. tity in	-> (17 -> (27) -> AS NOTE	IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	Immunity Immunity <td< td=""></td<>			

LEAD FREE 4

JEITA Phase 3

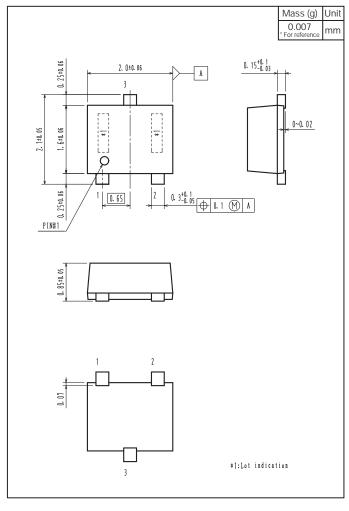
2. Taping configuration

2-1. Carrier tape size (unit:mm)

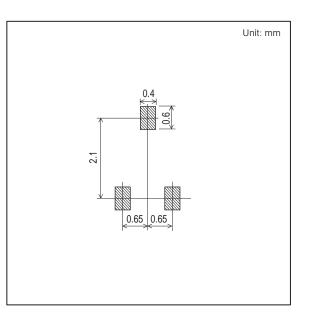


Those with pin 1 index on the feed hole side $\cdots \cdots TL$

Outline Drawing MCH3475-TL-E



Land Pattern Example



Note on usage : Since the MCH3475 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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